

AMENDMENT UNDER 37 C.F.R. § 1.111
U.S. Appln. No. 09/974,048

Copy 12 *Sub B2* 5. (Amended) A connection structure for connecting a terminal portion of a circuit board with an external terminal formed in an external circuit, wherein said terminal portion is provided with a nickel plating layer and a soldering bump provided on said terminal portion and a thickness of said nickel plating layer is within a range of 1.0 to 2.5 μm .